TE Internal #: 2337939-2

Board-to-Board, 64 Position, 1 mm [.039 in] Centerline, Vertical, Black, Height 11.25 mm [.442 in], PCI & PCI Express Connectors

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Connectors > PCB Connectors > Card Edge Connectors > PCI & PCI Express Connectors











Connector System: Board-to-Board

Number of Positions: 64

PCI Generation: 4

Centerline (Pitch): 1 mm [.039 in]

Contact Mating Area Plating Material Thickness: [15 µin]

Features

Product Type Features

Connector & Contact Terminates To	Printed Circuit Board
Connector System	Board-to-Board
Sealable	No

Configuration Features

Number of Positions	64
PCB Mount Orientation	Vertical
Ejector	Without

Body Features

Primary Product Color	Black
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Contact Features

PCB Contact Termination Area Plating Material Thickness	2.54 μm[100 μin]
Contact Mating Area Plating Material	Gold Flash
PCB Contact Termination Area Plating Material Finish	Matte
Contact Underplating Material	Nickel
PCB Contact Termination Area Plating Material	Tin



Contact Base Material	Copper Alloy
Contact Current Rating (Max)	1.1 A
	15 μin
Termination Features	
Termination Method to PCB	Surface Mount
Mechanical Attachment	
Connector Mounting Type	Board Mount
Housing Features	
Housing Material	LCP With 30% G.F
Centerline (Pitch)	1 mm[.039 in]
Dimensions	
Connector Length	39 mm[1.535 in]
Connector Height	11.25 mm[.442 in]
Connector Width	8.75 mm[.345 in]
Usage Conditions	
Operating Temperature Range	-40 - 85 °C[-40 - 185 °F]
Operation/Application	
Circuit Application	Signal
Industry Standards	
Bus Type	PCI Express
PCI Generation	4
Packaging Features	
Packaging Method	Box & Tray

Product Compliance

For compliance documentation, visit the product page on TE.com>

EU RoHS Directive 2011/65/EU	Compliant
EU ELV Directive 2000/53/EC	Compliant
China RoHS 2 Directive MIIT Order No 32, 2016	No Restricted Materials Above Threshold
EU REACH Regulation (EC) No. 1907/2006	Current ECHA Candidate List: JUNE 2024 (241) Candidate List Declared Against: JAN 2022 (223)



Does not contain REACH SVHC

ł	Low Halogen - Br, Cl, F, I < 900 ppm per homogenous material. Also BFR/CFR/PVC Free
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Solder Process Capability

Not reviewed for solder process capability

Product Compliance Disclaimer

This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulation, the information TE provides on SVHC in articles for this part number is based on the latest European Chemicals Agency (ECHA) 'Guidance on requirements for substances in articles' posted at this URL: https://echa.europa.eu/guidance-documents/guidance-on-reach

Compatible Parts



Customers Also Bought













Documents

CAD Files

3D PDF

3D

Customer View Model

ENG_CVM_CVM_2337939-2_A.2d_dxf.zip

English

Customer View Model

ENG_CVM_CVM_2337939-2_A.3d_igs.zip

English

Customer View Model

ENG_CVM_CVM_2337939-2_A.3d_stp.zip

English

By downloading the CAD file I accept and agree to the **Terms and Conditions** of use

Product Specifications

Product Specification

English

Agency Approvals

UL Report

English